

# Burn-In Chamber



This system evaluates the reliability of high-density semiconductor devices and performs large capacity screenings. Featuring excellent temperature uniformity performance and permissible heat generation load characteristics, this system accommodates a large capacity of burn-in boards (increased by 33%) and saves space with a compact design. It uses an HFC refrigerant with a zero ozone layer depletion coefficient and a damper open/close control system for ventilation control, and an electronic expansion valve provides control of the refrigerant flow rate for significant energy savings. In addition, all molded parts are quality marked and can be recycled as a resource.

Model	Target specimen	Temperature range
RBC-H	IC, discrete, other general semiconductor devices, various electronic parts, electronic units, and substrates	+70 to +150°C
RBC-M		+20 to +150°C
RBC-L		-30 to +150°C
RBC-U		-55 to +150°C

## Outside dimensions (mm)

Model	W	H	D
00 type	780	2050	1250
0 type	780	2050	1530
1 type	1060	2050	1250
2 type	1060	2050	1530
3 type	1060	2050	1250
4 type	1060	2050	1530
7 type	1360	2050	1250
8 type	1360	2050	1530
9 type	1680	2050	1250
10 type	1680	2050	1530
11 type	2300	2050	1250

12 type

2300

2050

1530

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Temperature Chamber Series



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Automotive Sensor Burn-In System

